UNITED STATES
SECURITIES AND EXCHANGE COMMISSION
Washington, DC 20549

FORM 8-K

CURRENT REPORT

Pursuant to Section 13 or 15(d) of the Securities Exchange Act of 1934

Date of Report (Date of earliest event reported) June 6, 2012

AMKOR TECHNOLOGY, INC.
(Exact name of registrant as specified in its charter)

DELAWARE	000-29472	23-1722724
(State or Other Jurisdiction of Incorporation)	(Commission File Number)	(IRS Employer Identification No.)

1900 SOUTH PRICE ROAD
CHANDLER, AZ 85286
(Address of Principal Executive Offices, including Zip Code)

(480) 821-5000
(Registrant's telephone number, including area code)

Check the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions:

☐ Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)

☐ Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)

☐ Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))

☐ Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c))

Item 7.01. Regulation FD Disclosure.

On June 7, 2012, Amkor Technology, Inc. will be participating in a non-deal investor road show in New York, NY sponsored by Citi, and on June 8, 2012, Amkor Technology, Inc. will be participating in the Credit Suisse Semi-Cap Equipment and EDA Conference, held in Boston, MA. Attached hereto as Exhibit 99.1 and incorporated by reference herein, is a copy of the materials to be presented to investors at these events. A copy of the investor presentation is available on the company's website: www.amkor.com.

The information in this Form 8-K and the exhibit attached hereto is being furnished and shall not be deemed "filed" for purposes of Section 18 of the Securities Exchange Act of 1934, as amended (the "Exchange Act") or otherwise subject to the liabilities of that section, nor shall it be deemed incorporated by reference in any filing under the Securities Act of 1933, as amended, or the Exchange Act, regardless of any general incorporation language in such filing.

Item 9.01. Financial Statements and Exhibits.

(d) Exhibits.

99.1 Investor Presentation dated June 2012, which is furnished (not filed) herewith.

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

AMKOR TECHNOLOGY, INC.

By: /s/ Gil C. Tily
Gil C. Tily
Executive Vice President, Chief Administrative Officer and General Counsel

Date: June 6, 2012

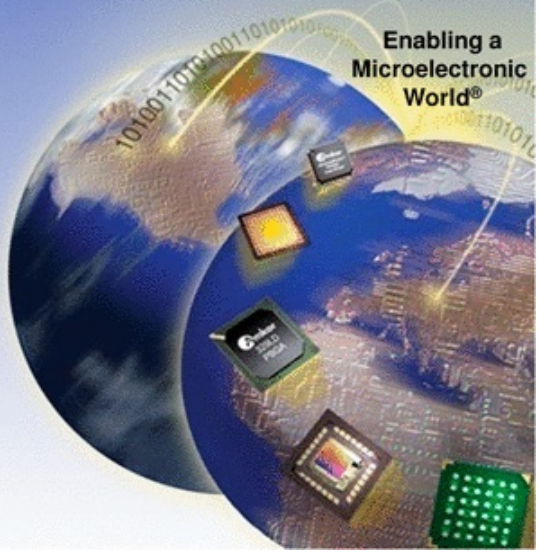
EXHIBIT INDEX:

Exhibit	Description
99.1	Investor Presentation dated June 2012

Exhibit 99.1

Amkor Technology, Inc.
Investor Presentation

June 2012



Amkor Technology®

Disclaimer

Forward-Looking Statement Disclaimer

All information and other statements contained in this presentation, other than statements of historical fact, constitute forward-looking statements within the meaning of federal securities laws. These forward-looking statements involve a number of risks, uncertainties, assumptions and other factors that could affect our future results and cause actual results and events to differ materially from our historical and expected results and those expressed or implied in these forward-looking statements. Our historical financial information, and the risks and other important factors that could affect the outcome of the events set forth in these statements and that could affect our operating results and financial condition, are contained in our filings with the Securities and Exchange Commission, including our Form 10-K for the 2011 year and subsequent filings. We undertake no obligation to review or update any forward-looking statements to reflect events or circumstances occurring after this presentation.

Policy Regarding Prior Guidance and Forward-Looking Statements

From time to time we may provide financial guidance in our earnings releases and make other forward-looking statements. Our financial guidance and other forward-looking statements are effective only on the date given. In accordance with our policy, we will not update, reaffirm or otherwise comment on any prior financial guidance or other forward-looking statements in connection with this presentation. No reference made to any prior financial guidance or other forward-looking statements in connection with this presentation should be construed to update, reaffirm or otherwise comment on such prior financial guidance or other forward-looking statements.

Key Business Highlights

One of the World's Leading Outsourced Semiconductor Packaging and Test Providers

Industry Pioneer and Technology Leader Driving Innovation for Over 40 Years

In the Right Markets with the Right Customers

Strong Competitive Position

Favorable OSAT Industry Trends

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Key Financial Highlights

Continued Focus on Profitable Growth and Strong Cash Flow Generation

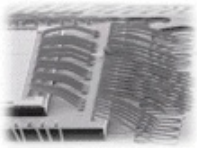
Managing Profitability Through Industry Cycles

Strong Balance Sheet with Debt to EBITDA of 2.6x

Industry-Leading 10% ROIC[1,3] Above 9% WACC

Well Positioned for Future Growth

$2.77 Billion Net Sales[1]	$514 Million EBITDA[1,2]	$78 Million Net Income[1]



(1) LTM 1Q12
(2) EBITDA is defined as net income before interest expense, income tax expense and depreciation and amortization - Refer to reconciliation of Non-GAAP measures in the appendix
(3) Return on invested capital ("ROIC") is defined as net operating profit after tax divided by average invested capital (the sum of average debt plus average equity less average cash) - Refer to the financial calculation table in the appendix for the calculation of ROIC

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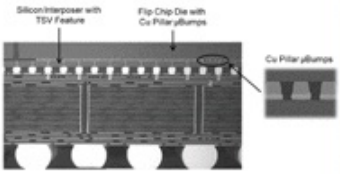
Growth Drivers

End Markets

- In the Right Markets
- Significant Penetration in Key Devices
- Deep Ties with the Right Customers
- Strong OEM Presence



Technology and R&D

- Flip Chip Growth
- Fine Pitch Copper Pillar Platform
- Wafer-Level Processes
- 3D Packaging
- MEMS
- Copper Wirebonding

Packaging and Test Industry

- Semiconductor Unit Growth
- IDM Outsourcing and "Fab-Lite" Model
- Growth of Fab-Less Design Houses
- Collaboration and Innovation

Note: Silicon interposer image courtesy of Xilinx, TSMC, and Amkor

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In the Right Markets

	Smartphone	▪ Cumulative 5.1 Billion Unit Sales from 2012-2016 (22% CAGR)[1] ▪ 55% of Handsets by 2016[1]	QUALCOMM, Texas Instruments, infineon, SAMSUNG, Micron, TOSHIBA
	Tablet	▪ Cumulative 1.3 Billion Unit Sales from 2012- 2016 (41% CAGR)[1] ▪ 2016 Tablet Traffic at 1.1 Exabytes per Month (Equal to Entire Global Mobile Network in 2012)[2]	
	Consumer Electronics	▪ Gaming Consoles ▪ "Always Connected" Devices ▪ Digital Home	SONY, Panasonic, IBM, TOSHIBA, BROADCOM
	Networking	▪ 2015 Global IP Traffic at 81 Exabytes per Month (32% CAGR vs 2010)[2] ▪ 2016 Global Mobile Data Traffic at 11 Exabytes per Month (18-Fold Growth vs 2011)[2]	LSI, ALTERA, BROADCOM, XILINX, AVAGO TECHNOLOGIES

[1] Gartner. Mobile Devices Forecast Update. March 2012
[2] Cisco Visual Networking Index Forecast. February 2012 and February 2011

End Market Summary

Communications 43%	Consumer 24%	Computing 12%	Networking 12%	Other 9%
Smartphone	Gaming	PC / Laptop	Server	Automotive
Tablet	Television	Hard Disc Drive	Router	Industrial
Wireless LAN	Set Top Box	Peripherals	Switch	

Note: Percentages represent share of LTM 1Q12 Net Sales.

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Significant Penetration in Key Devices

Smartphone & Tablet	Gaming Console	Digital Home	Networking Server
Applications Processor	CPU	CPU	CPU
Digital Baseband	GPU	Signal / Image Processor	ASIC / PLD
Memory	Memory	Memory	Memory
Audio Processor	Video Controller	Digital Tuner Decoder	I/O Control Bus
WiFi, Bluetooth, GPS, FM Radio	I/O Control Bus	Audio Processors	
Power Management	WiFi, Bluetooth, GPS, FM Radio		
MEMS Sensors	MEMS Sensors		
RF / RFPA			
Touch Screen Controller			

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Deep Ties with the Right Customers

Customer Share of 2011 Net Sales

Top 10 - 61%[1] / Top 25 - 83%

ALTERA
LSI
ANALOG DEVICES
QUALCOMM
BROADCOM
ST
infineon
TEXAS INSTRUMENTS
IBM
TOSHIBA

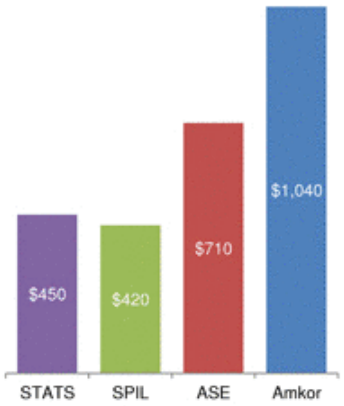
[1] Top 10 customers represent 62% of Net Sales for LTM 1Q12

Flip Chip & Advanced Packaging Leader

- Migration to Flip Chip, 3D and Advanced Packaging Continues to Accelerate
- Driven by Strong Demand for Smartphones, Tablets, Gaming Devices, Network Infrastructure
- Enhances Device Performance, Reduces Power Consumption and Form Factors
- Higher Gross Margin and Returns Versus Wirebond

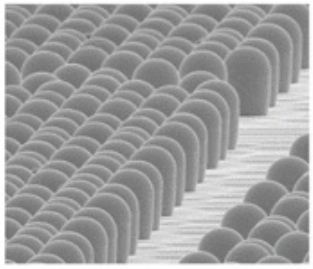
LTM 1Q12 Flip Chip & Advanced Packaging Revenue

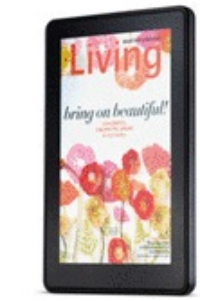
($ in millions)

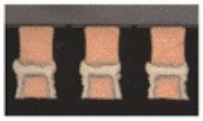


Source: Company Press Releases

Fine Pitch Copper Pillar Flip Chip







Provides Significant Improvement Over Solder Bump

Small and fine pitch pillars, designed for thin die and reduced package height, high thermal and electrical performance, lower cost

Handheld, High Performance, Low Power Devices

Applications Processors, Digital Baseband, Power Management, Networking ASICs, Digital TV ASICs

Launched in 2010, Over 125 Million Units Sold

Industry-Leading Platform Being Adopted by Multiple Customers

Enabling Technology for 2.5D and 3D Packaging with Through Silicon Vias

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2.5D & 3D Packaging Driving Performance Improvements

Amkor Technology®

Fine Pitch Copper Pillar

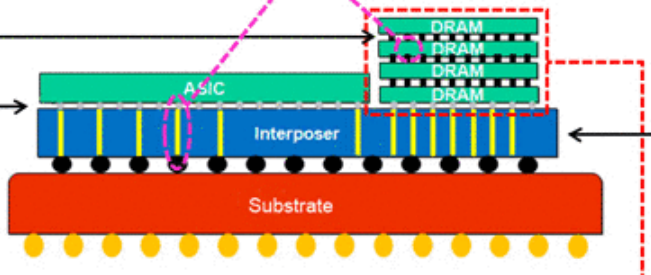
- Interconnect for TSV-based die stacking
- Die-to-Die, Die-to-Interposer, Die-to-Substrate, Interposer-to-Substrate

Through Silicon Via (TSV)

- Vertical connections through die or interposer
- Short length, high density
- Electrical, thermal, form factor advantages

2.5D Silicon Interposer

- Passive silicon with TSVs
- High density die integration
- Large form factor
- Network, GPU, CPU



2.5D & 3D Advantages

- Integration of multiple heterogeneous die
- Higher performance, wider bandwidth
- Reduced power consumption
- Active and passive components
- Lower design and package costs
- Faster time-to-market

3D Vertical Stacking

- Multiple die with TSVs
- Attached to interposer or substrate
- Small form factor
- Applications Processors, Memory

Research & Development

Focus Areas	Modeling & Simulation	Collaboration Across Supply Chain
3D Packaging: Silicon Interposers, TSV Fine Pitch Copper Pillar Wafer Level Process Copper Wirebond MEMS Manufacturing Cost Reductions Test	Cost and Performance Optimization Mechanical Electrical Thermal Material Optimization Process Stability Reliability Enhancement Faster Time-to-Market	System Designers: Integration, Package Performance Requirements and Roadmaps Materials and Equipment Suppliers: Engineered Materials and Processes Key Customers for Platform Solutions

Over 400 Staff Worldwide. $65 Million Investment in 2011

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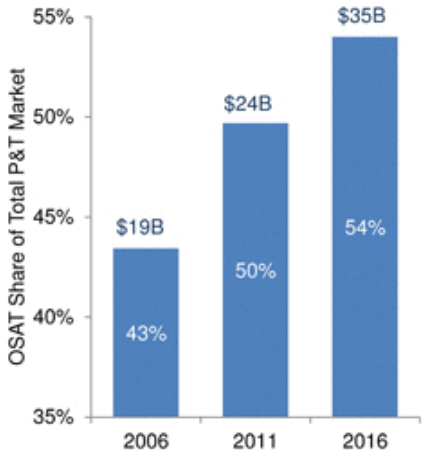
Packaging and Test Industry Growth Drivers

- Semiconductor Unit Growth
  - 8% CAGR from 2011 to 2016[1]
- IDM Outsourcing
  - "Fab-Lite" model gaining momentum
  - Some not investing in new packaging and test technologies
  - Some shedding assets to OSATs
- Growth of Fabless Design Houses[1]
  - $65 billion revenue
  - 25% of total IC market in 2011
  - Up from 9% in 2000
- Collaboration and Innovation
  - OSATs no longer just overflow capacity

Outsourced Packaging & Test Market



[1] The McClean Report 2012.

Source: Gartner Semiconductor Assembly and Test Services, Worldwide, 1Q12 Update

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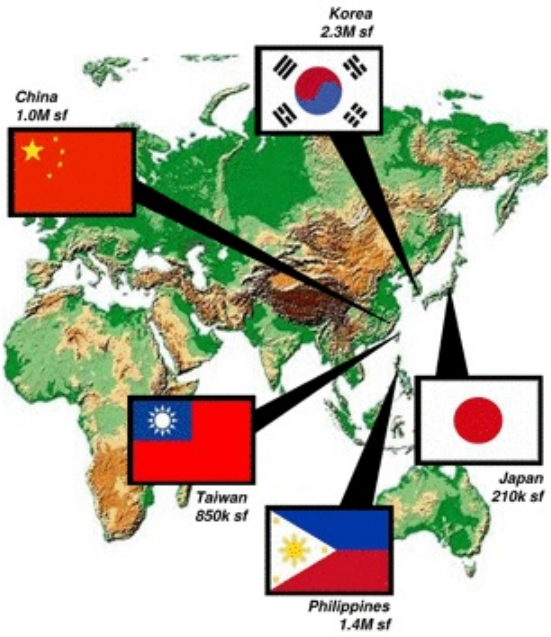
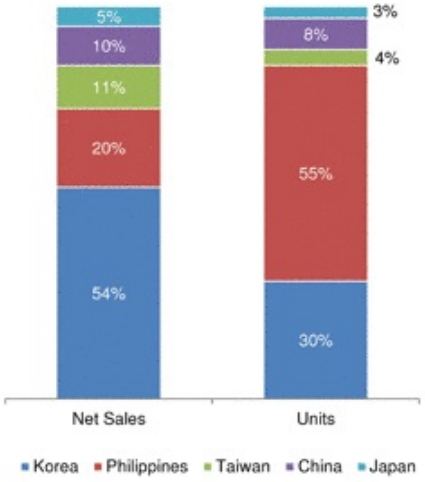
World-Class Manufacturing Infrastructure, Scale and Scope



5.8 Million Sq. Ft. Manufacturing Space

LTM 1Q12 Net Sales and Packaged Units by Factory Location



K5 Facility

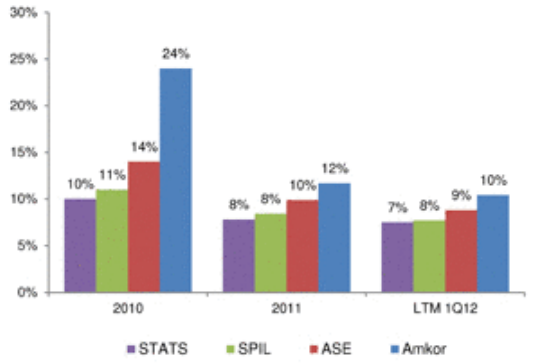
- New Factory and State-of-the-Art R&D Center
- Seoul, Korea Metropolitan Area
- Flagship Site in Prime Location Near Incheon Airport
  - Improved transportation and logistics
  - First class site for customers
  - Attract top engineering and operations talent
- Advanced Packaging and Test Services Focus
- Tax Incentives Available for Investment

Strong Competitive Position

- Industry-Leading ROIC
- 10% ROIC Above 9% WACC
- Consistent Ability to Generate Strong Returns Over the Cycle
- Disciplined Capital Spending Closely Aligned with Customer Opportunities

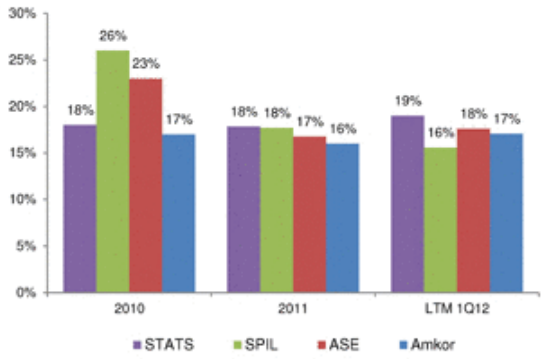
Return on Invested Capital (ROIC)

ROIC is defined as net operating profit after tax divided by average invested capital



Capital Intensity

Capital Intensity is defined as capital additions as a percentage of net sales



* SPIL based on purchases of property, plant and equipment as a percentage of net sales

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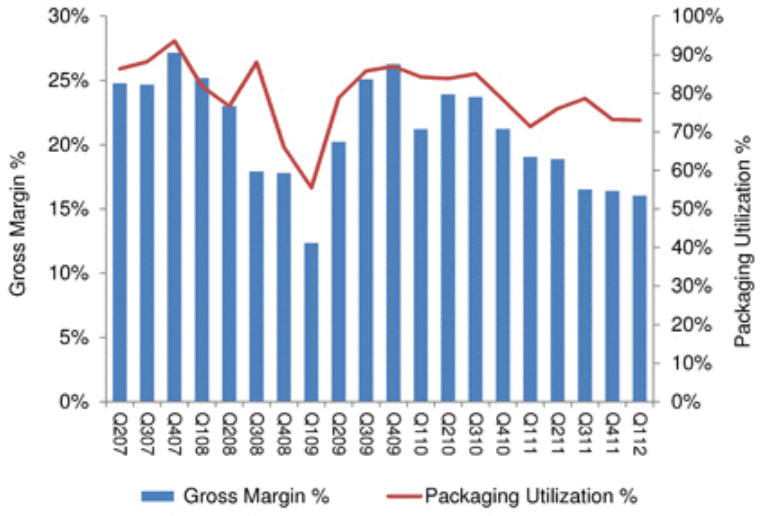
Utilization Significant Gross Margin Driver



- Flip Chip & Advanced Packages Generate Higher Gross Margin Than Wirebond
- Manage Costs in Sync with Demand Over Cycles
- Other Drivers
  - F/X
  - Gold Prices
  - ASPs

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First Quarter 2012 Summary

(In millions, except per share data)	1Q 2011	4Q 2011	1Q 2012
Net Sales	$665	$684	$655
Gross Margin	19%	16%	16%
Net Income	$25	$25	$12
Earnings Per Diluted Share	$0.10	$0.11	$0.06
Free Cash Flow(1)	$6	($1)	($65)
EBITDA(2)	$133	$130	$126
Packaging Utilization	71%	73%	73%

(1) Free cash flow is defined as operating cash flow less purchases of property, plant and equipment
(2) EBITDA is defined as net income before depreciation and amortization, interest expense and income tax expense - Refer to reconciliation of Non-GAAP measures in the appendix

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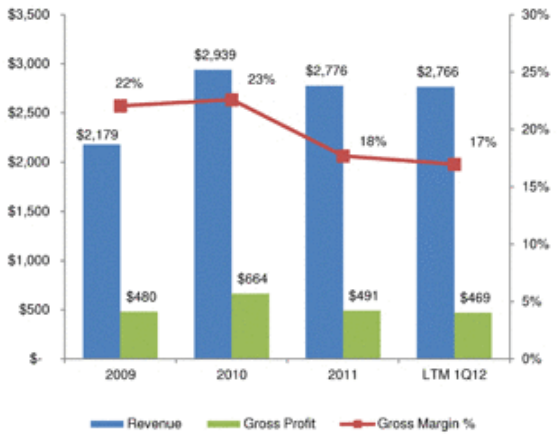
Profitability Trends

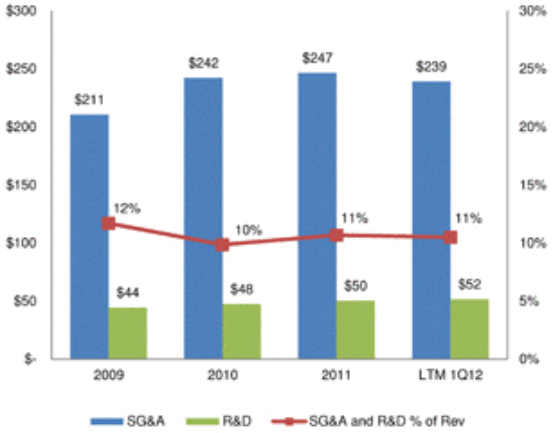
Revenue and Gross Profit

($ in millions)



Selling, General & Administrative and Research & Development

($ in millions)



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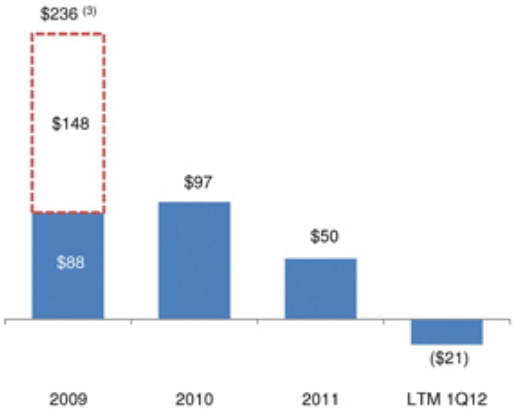
Free Cash Flow and EBITDA



(1) Free cash flow is defined as operating cash flow less purchases of property, plant and equipment - Refer to reconciliation of Non-GAAP measures in the appendix
(2) EBITDA is defined as net income before depreciation and amortization, interest expense and income tax expense - Refer to reconciliation of Non-GAAP measures in the appendix
(3) Excludes payments relating to Korean severance obligations and the resolution of a patent license dispute of which $148 million was paid in 2009

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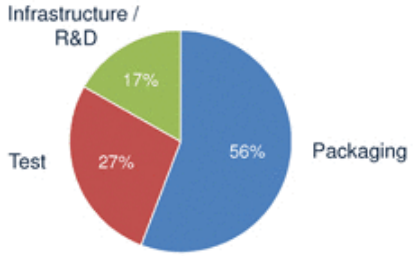
Capital Additions and Capital Intensity

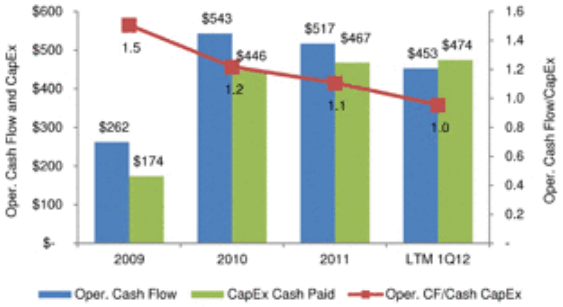
- Increased 2012 Capital Additions From $300 Million to $550 Million to Largely Support Second Half Demand for Smartphones and Tablets from Major Customers
- K5 Facility
  - $350 million for land and buildings over 3 to 4 years
  - $30 million cash paid in 2012, $70 million paid in 2013
  - $100 million paid in 2012 and 2013 accrues in 2012 (incremental to $550 million previously announced)
  - Construction commences in 2014
  - Operations commence in 2015 or 2016

LTM 1Q12 Capital Additions



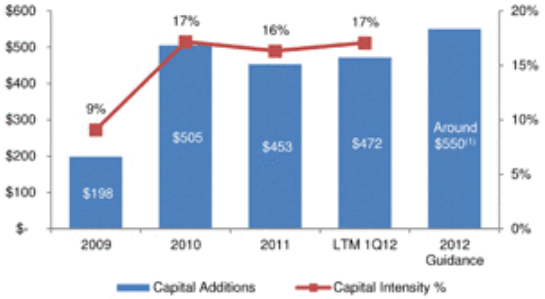
Operating Cash Flow and CapEx

($ in millions)



Capital Intensity

Capital Intensity is defined as capital additions as a percentage of net sales ($ in millions)

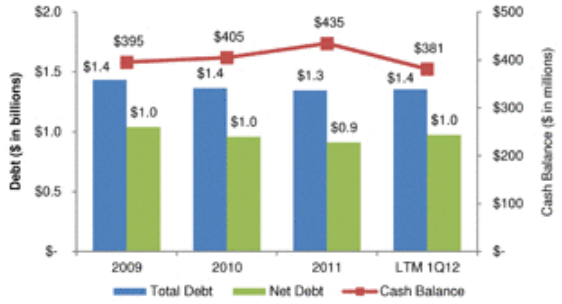


[1] Excludes K5 Facility investment of approximately $100 million

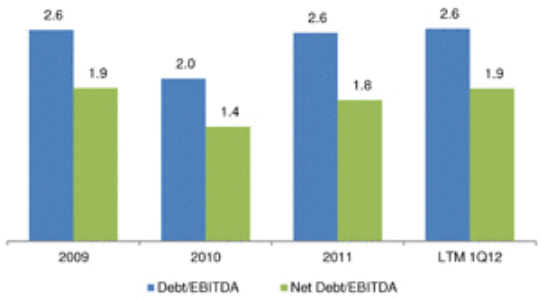
Credit Profile

- Debt Reductions 2005 to LTM 1Q12
  - Total Debt Down $0.8 Billion
  - Net Debt Down $1.0 Billion

Total Debt, Net Debt and Cash Balance

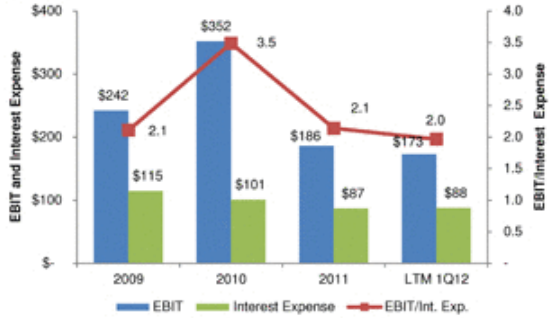


Debt/EBITDA and Net Debt/EBITDA



EBIT and Interest Expense

($ in millions)



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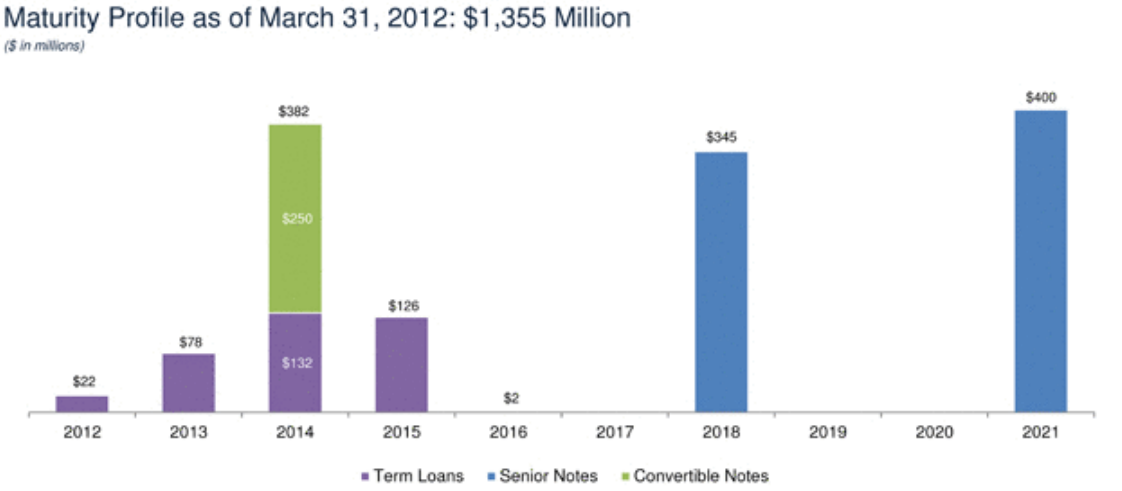
Debt Maturities



Callable Notes	Due	Balance ($M)	First Call Date	Call Price
7.375% Senior Notes	May 2018	$345	May 2014	103.688
6.625% Senior Notes	June 2021	$400	June 2015	104.969

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Appendix

Financial Reconciliation Tables

($ in millions)	2009	2010	2011	LTM 1Q12	1Q11	4Q11	1Q12
Net Cash Provided by Operating Activities	**$262**	**$543**	**$517**	**$453**	**$120**	**$141**	**$56**
Less: Purchases of Property, Plant and Equipment	(174)	(446)	(467)	(474)	(114)	(142)	(121)
Free Cash Flow*	**$88**	**$97**	**$50**	**($21)**	**$6**	**($1)**	**($65)**
Property, Plant and Equipment Additions							
(Capital Additions)	**$198**	**$505**	**$453**	**$472**	**$105**	**$128**	**$124**
Less: Net Change in Related Accounts Payable and Deposits	(24)	(59)	14	2	9	14	(3)
Purchases of Property, Plant and Equipment	**$174**	**$446**	**467**	**474**	**$114**	**$142**	**$121**
Net Income	**$156**	**$232**	**$92**	**$78**	**$25**	**$25**	**$12**
Plus: Interest Expense (Including Related Party)	115	101	87	88	22	22	22
Plus: Income Tax Expense (Benefit)	(29)	19	7	7	3	(3)	3
EBIT*	**242**	**352**	**186**	**173**	**50**	**44**	**37**
Plus: Depreciation & Amortization	305	324	335	341	83	86	89
EBITDA*	**$547**	**$676**	**$521**	**$514**	**$133**	**$130**	**$126**

* See discussion of Non-GAAP measures on following page

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Financial Reconciliation Tables

($ in millions)	**LTM 1Q12**
Operating Income	**$178**
Income Tax Expense	(7)
Net Operating Profit After Tax (NOPAT)	**$171**
Average Debt	**$1,299**
Plus: Average Equity	728
Less: Average Cash	(387)
Average Invested Capital	**$1,640**
Return on Invested Capital (ROIC)	**10%**
(NOPAT / Average Invested Capital)	

We define free cash flow as net cash provided by operating activities less purchases of property, plant and equipment. Free cash flow is not defined by U.S. GAAP. We believe free cash flow to be relevant and useful information to our investors because it provides them with additional information in assessing our liquidity, capital resources and financial operating results. Our management uses free cash flow in evaluating our liquidity, our ability to service debt and our ability to fund capital additions. However, free cash flow has certain limitations, including that it does not represent the residual cash flow available for discretionary expenditures since other, non-discretionary expenditures, such as mandatory debt service, are not deducted from the measure. The amount of mandatory versus discretionary expenditures can vary significantly between periods. This measure should be considered in addition to, and not as a substitute for, or superior to, other measures of liquidity or financial performance prepared in accordance with U.S. GAAP, such as net cash provided by operating activities. Furthermore, our definition of free cash flow may not be comparable to similarly titled measures reported by other companies.

We define EBIT as net income before interest expense and income tax expense. We define EBITDA as EBIT before depreciation and amortization. EBIT and EBITDA are not defined by generally accepted accounting principles. However, we believe EBIT and EBITDA to be relevant and useful information to our investors because they provide investors with additional information in assessing our financial operating results. Our management uses EBIT and EBITDA in evaluating our operating performance, our ability to service debt and our ability to fund capital additions. However, these measures should be considered in addition to, and not as a substitute for, or superior to, operating income, net income or other measures of financial performance prepared in accordance with generally accepted accounting principles, and our definitions of EBIT and EBITDA may not be comparable to similarly titled measures reported by other companies.

We define return on invested capital ("ROIC") as net operating profit after tax divided by average invested capital (the sum of average debt plus average equity less average cash). ROIC is not defined by U.S. GAAP. However, we believe ROIC is relevant and useful information for our investors and management in evaluating whether our capital investments are generating stockholder value.